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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	DMA, LCD, POR, PWM, WDT
Number of I/O	57
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f968-b-gqr

List of Tables

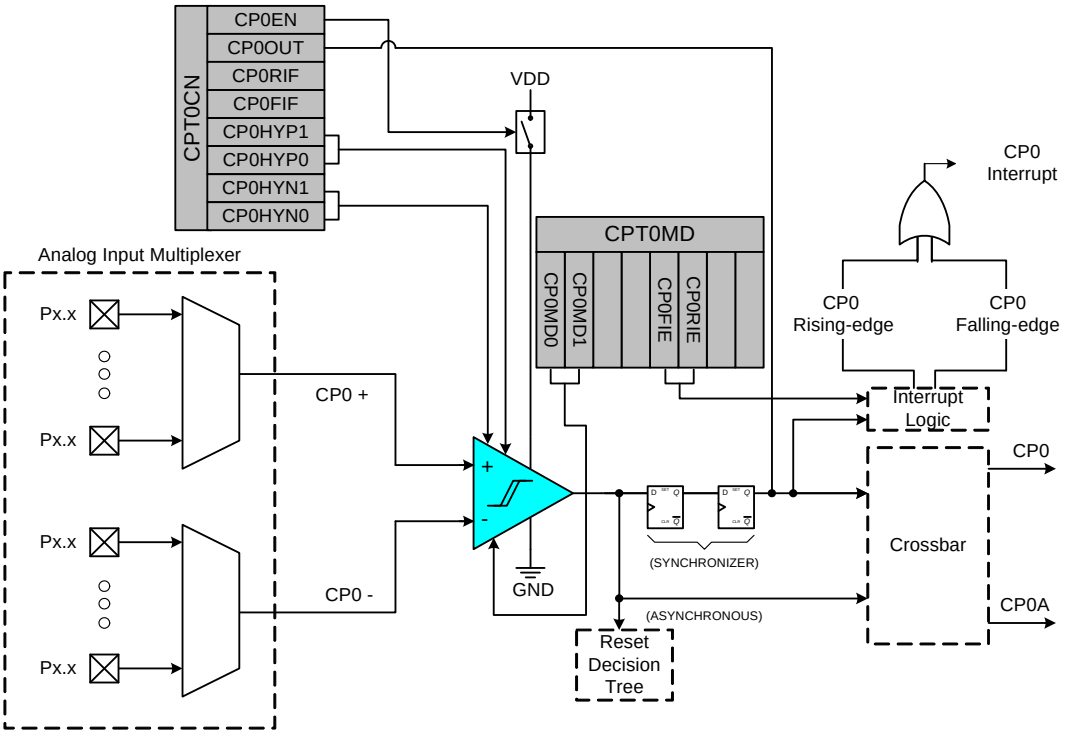

Figure 1.15. Comparator 0 Functional Block Diagram

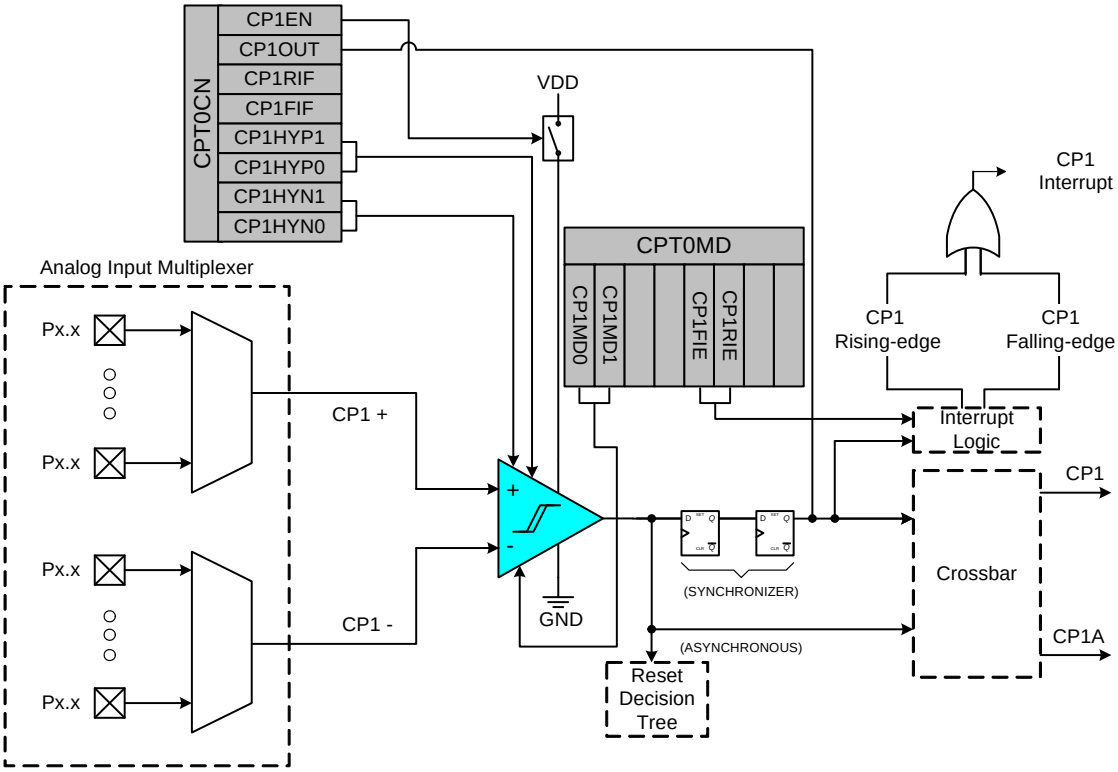

Figure 1.16. Comparator 1 Functional Block Diagram

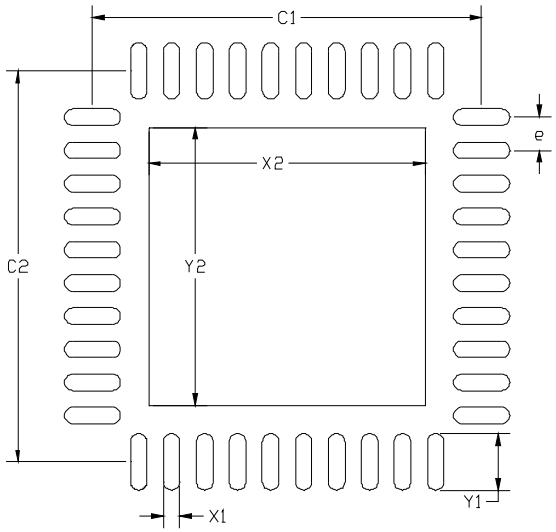

Figure 3.8. QFN-40 Landing Diagram

Table 3.6. QFN-40 Landing Diagram Dimensions

Dimension	Min	Max	Dimension	Min	Max
C1	5.80	5.90	X2	4.10	4.20
C2	5.80	5.90	Y1	0.75	0.85
e	0.50 BSC		Y2	4.10	4.20
X1	0.15	0.25			

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimension and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-SM-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

5. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

6. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
7. The stencil thickness should be 0.125 mm (5 mils).
8. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
9. A 4x4 array of 0.80 mm square openings on a 1.05 mm pitch should be used for the center ground pad.

Card Assembly

10. A No-Clean, Type-3 solder paste is recommended.
11. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

Table 4.4. Digital Supply Current with DC-DC Converter Disabled

–40 to +85 °C, 25 MHz system clock unless otherwise specified.

Parameter	Condition	Min	Typ	Max	Unit
Digital Supply Current—Active Mode, No Clock Gating (PCLKACT=0x0F) (CPU Active, fetching instructions from flash)					
I_{BAT} [1, 2]	V_{BAT} = 1.8–3.8 V, F = 24.5 MHz (includes precision oscillator current)	—	4.9	5.5	mA
	V_{BAT} = 1.8–3.8 V, F = 20 MHz (includes low power oscillator current)	—	3.9	—	mA
	V_{BAT} = 1.8 V, F = 1 MHz V_{BAT} = 3.8 V, F = 1 MHz (includes external oscillator/GPIO current)	— —	175 190	— —	µA µA
	V_{BAT} = 1.8–3.8 V, F = 32.768 kHz (includes SmaRTClock oscillator current)	—	85	—	µA
I_{BAT} Frequency Sensitivity[1,3,4]	V_{BAT} = 1.8–3.8 V, T = 25 °C	—	183	—	µA/MHz
Digital Supply Current—Active Mode, All Peripheral Clocks Disabled (PCLKACT=0x00) (CPU Active, fetching instructions from flash)					
I_{BAT} [1, 2]	V_{BAT} = 1.8–3.8 V, F = 24.5 MHz (includes precision oscillator current)	—	3.9	—	mA
	V_{BAT} = 1.8–3.8 V, F = 20 MHz (includes low power oscillator current)	—	3.1	—	mA
	V_{BAT} = 1.8 V, F = 1 MHz V_{BAT} = 3.8 V, F = 1 MHz (includes external oscillator/GPIO current)	— —	165 180	— —	µA µA
I_{BAT} Frequency Sensitivity[1, 3]	V_{BAT} = 1.8–3.8 V, T = 25 °C	—	140	—	µA/MHz

Notes:

1. Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, $, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.
2. Includes oscillator and regulator supply current.
3. Based on device characterization data; Not production tested.
4. Measured with one-shot enabled.
5. Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.
6. Using SmaRTClock osillator with external 32.768 kHz CMOS clock. Does not include crystal bias current.
7. Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x00.

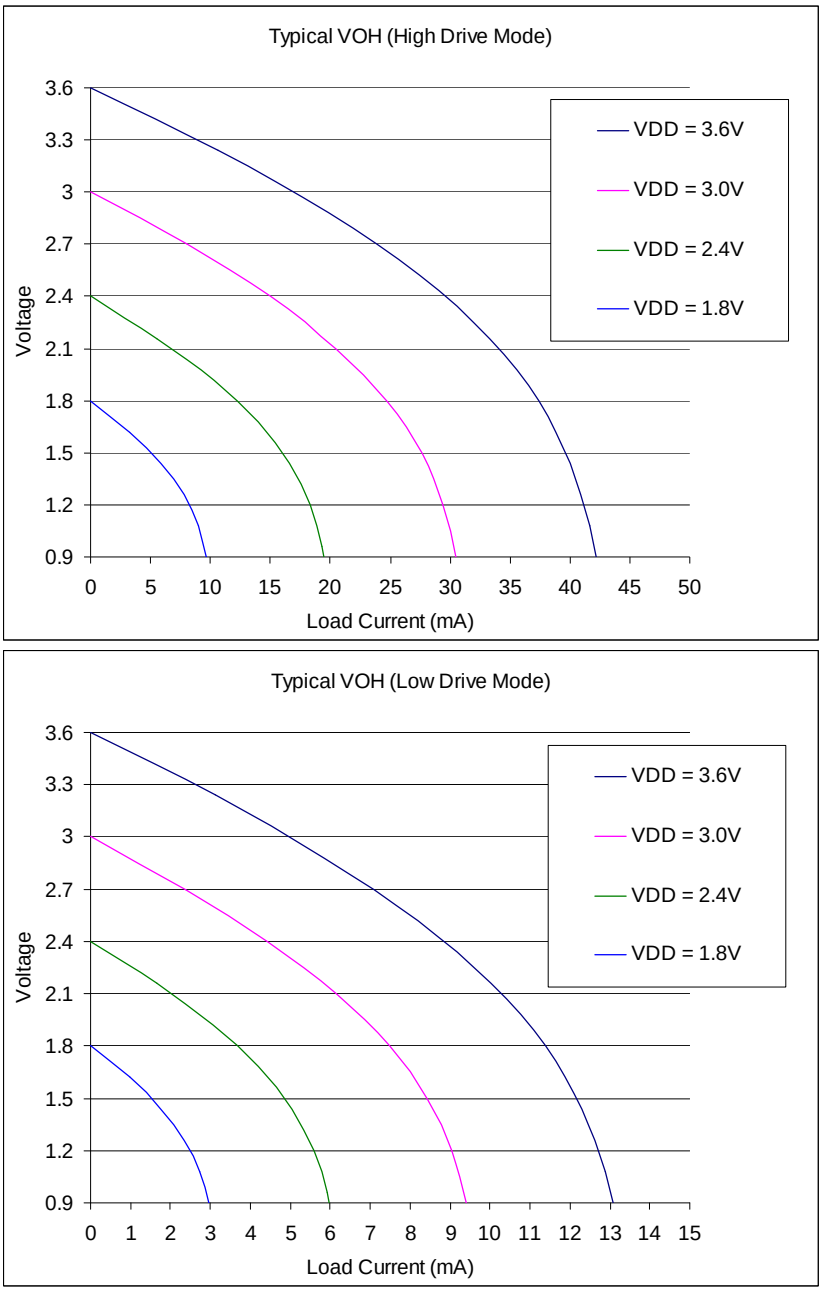

Figure 4.2. Typical VOH Curves, 1.8–3.6 V

SFR Definition 5.1. ADC0CN: ADC0 Control

Bit	7	6	5	4	3	2	1	0
Name	AD0EN	BURSTEN	AD0INT	AD0BUSY	AD0WINT	ADC0CM[2:0]		
Type	R/W	R/W	R/W	W	R/W	R/W		
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xE8; bit-addressable;

Bit	Name	Function
7	AD0EN	**ADC0 Enable.** 0: ADC0 Disabled (low-power shutdown). 1: ADC0 Enabled (active and ready for data conversions).
6	BURSTEN	**ADC0 Burst Mode Enable.** 0: ADC0 Burst Mode Disabled. 1: ADC0 Burst Mode Enabled.
5	AD0INT	**ADC0 Conversion Complete Interrupt Flag.** Set by hardware upon completion of a data conversion (BURSTEN=0), or a burst of conversions (BURSTEN=1). Can trigger an interrupt. Must be cleared by software.
4	AD0BUSY	**ADC0 Busy.** Writing 1 to this bit initiates an ADC conversion when ADC0CM[2:0] = 000.
3	AD0WINT	**ADC0 Window Compare Interrupt Flag.** Set by hardware when the contents of ADC0H:ADC0L fall within the window specified by ADC0GTH:ADC0GTL and ADC0LTH:ADC0LTL. Can trigger an interrupt. Must be cleared by software.
2:0	ADC0CM[2:0]	**ADC0 Start of Conversion Mode Select.** Specifies the ADC0 start of conversion source. 000: ADC0 conversion initiated on write of 1 to AD0BUSY. 001: ADC0 conversion initiated on overflow of Timer 0. 010: ADC0 conversion initiated on overflow of Timer 2. 011: ADC0 conversion initiated on overflow of Timer 3. 1xx: ADC0 conversion initiated on rising edge of CNVSTR.

SFR Definition 12.1. CRC0CN: CRC0 Control

Bit	7	6	5	4	3	2	1	0
Name				CRC0SEL	CRC0INIT	CRC0VAL	CRC0PNT[1:0]	
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Reset	0	0	0	0	0	0	0	0

SFR Page = 0xF; SFR Address = 0x92

Bit	Name	Function
7:5	Unused	Read = 000b; Write = Don't Care.
4	CRC0SEL	**CRC0 Polynomial Select Bit.** This bit selects the CRC0 polynomial and result length (32-bit or 16-bit). 0: CRC0 uses the 32-bit polynomial 0x04C11DB7 for calculating the CRC result. 1: CRC0 uses the 16-bit polynomial 0x1021 for calculating the CRC result.
3	CRC0INIT	**CRC0 Result Initialization Bit.** Writing a 1 to this bit initializes the entire CRC result based on CRC0VAL.
2	CRC0VAL	**CRC0 Set Value Initialization Bit.** This bit selects the set value of the CRC result. 0: CRC result is set to 0x00000000 on write of 1 to CRC0INIT. 1: CRC result is set to 0xFFFFFFFF on write of 1 to CRC0INIT.
1:0	CRC0PNT[1:0]	**CRC0 Result Pointer.** Specifies the byte of the CRC result to be read/written on the next access to CRC0DAT. The value of these bits will auto-increment upon each read or write. For CRC0SEL = 0: 00: CRC0DAT accesses bits 7–0 of the 32-bit CRC result. 01: CRC0DAT accesses bits 15–8 of the 32-bit CRC result. 10: CRC0DAT accesses bits 23–16 of the 32-bit CRC result. 11: CRC0DAT accesses bits 31–24 of the 32-bit CRC result. For CRC0SEL = 1: 00: CRC0DAT accesses bits 7–0 of the 16-bit CRC result. 01: CRC0DAT accesses bits 15–8 of the 16-bit CRC result. 10: CRC0DAT accesses bits 7–0 of the 16-bit CRC result. 11: CRC0DAT accesses bits 15–8 of the 16-bit CRC result.

SFR Definition 13.5. CRC1OUTL: CRC1 Output LSB

Bit	7	6	5	4	3	2	1	0
Name	CRC1OUTL[7:0]							
Type	R	R	R	R	R	R	R	R
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x2; SFR Address = 0xBA; Not Bit-Addressable

Bit	Name	Function
7:0	CRC1OUTL[7:0]	**CRC1 Output LSB**

SFR Definition 13.6. CRC1OUTH: CRC1 Output MSB

Bit	7	6	5	4	3	2	1	0
Name	CRC1OUTH[7:0]							
Type	R	R	R	R	R	R	R	R
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x2; SFR Address = 0xBB; Not Bit-Addressable

Bit	Name	Function
7:0	CRC1OUTH[7:0]	**CRC1 Output MSB.**

The level of flash security depends on the flash access method. The three flash access methods that can be restricted are reads, writes, and erases from the C2 debug interface, user firmware executing on unlocked pages, and user firmware executing on locked pages. Table 18.1 summarizes the flash security features of the C8051F96x devices.

Table 18.1. Flash Security Summary

Action	C2 Debug Interface	User Firmware executing from:	
		an unlocked page	a locked page
Read, Write or Erase unlocked pages (except page with Lock Byte)	Permitted	Permitted	Permitted
Read, Write or Erase locked pages (except page with Lock Byte)	Not Permitted	Flash Error Reset	Permitted
Read or Write page containing Lock Byte (if no pages are locked)	Permitted	Permitted	Permitted
Read or Write page containing Lock Byte (if any page is locked)	Not Permitted	Flash Error Reset	Permitted
Read contents of Lock Byte (if no pages are locked)	Permitted	Permitted	Permitted
Read contents of Lock Byte (if any page is locked)	Not Permitted	Flash Error Reset	Permitted
Erase page containing Lock Byte (if no pages are locked)	Permitted	Flash Error Reset	Flash Error Reset
Erase page containing Lock Byte—Unlock all pages (if any page is locked)	C2 Device Erase Only	Flash Error Reset	Flash Error Reset
Lock additional pages (change 1s to 0s in the Lock Byte)	Not Permitted	Flash Error Reset	Flash Error Reset
Unlock individual pages (change 0s to 1s in the Lock Byte)	Not Permitted	Flash Error Reset	Flash Error Reset
Read, Write or Erase Reserved Area	Not Permitted	Flash Error Reset	Flash Error Reset

C2 Device Erase—Erases all flash pages including the page containing the Lock Byte.

Flash Error Reset—Not permitted; Causes Flash Error Device Reset (FERROR bit in RSTSRC is '1' after reset).

- All prohibited operations that are performed via the C2 interface are ignored (do not cause device reset).

- Locking any flash page also locks the page containing the Lock Byte.

- Once written to, the Lock Byte cannot be modified except by performing a C2 Device Erase.

- If user code writes to the Lock Byte, the Lock does not take effect until the next device reset.

21. Voltage Regulator (VREG0)

C8051F96x devices include an internal voltage regulator (VREG0) to regulate the internal core supply to 1.8 V from a VDD/DC+ supply of 1.8 to 3.6 V. Electrical characteristics for the on-chip regulator are specified in the Electrical Specifications chapter.

The REG0CN register allows the Precision Oscillator Bias to be disabled, reducing supply current in all non-sleep power modes. This bias should only be disabled when the precision oscillator is not being used.

The internal regulator (VREG0) is disabled when the device enters sleep mode and remains enabled when the device enters suspend mode. See Section “19. Power Management” on page 257 for complete details about low power modes.

SFR Definition 21.1. REG0CN: Voltage Regulator Control

Bit	7	6	5	4	3	2	1	0
Name				OSCBIAS				
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	1	0	0	0	0

SFR Page = 0x0; SFR Address = 0xC9

Bit	Name	Function
7:5	Reserved	Read = 000b. Must Write 000b.
4	OSCBIAS	**Precision Oscillator Bias.** When set to 1, the bias used by the precision oscillator is forced on. If the precision oscillator is not being used, this bit may be cleared to 0 to to save supply current in all non-Sleep power modes.
3:0	Reserved	Read = 0000b. Must Write 0000b.

21.1. Voltage Regulator Electrical Specifications

See Table 4.17 on page 75 for detailed Voltage Regulator Electrical Specifications.

23.4. Special Function Registers for Selecting and Configuring the System Clock

The clocking sources on C8051F96x devices are enabled and configured using the OSCICN, OSCICL, OSCXCN and the SmaRTClock internal registers. See Section “24. SmaRTClock (Real Time Clock)” on page 295 for SmaRTClock register descriptions. The system clock source for the MCU can be selected using the CLKSEL register. To minimize active mode current, the oneshot timer which sets Flash read time should by bypassed when the system clock is greater than 10 MHz. See the FLSCL register description for details.

The clock selected as the system clock can be divided by 1, 2, 4, 8, 16, 32, 64, or 128. When switching between two clock divide values, the transition may take up to 128 cycles of the undivided clock source. The CLKRDY flag can be polled to determine when the new clock divide value has been applied. The clock divider must be set to "divide by 1" when entering Suspend or Sleep Mode.

The system clock source may also be switched on-the-fly. The switchover takes effect after one clock period of the slower oscillator.

SFR Definition 23.1. CLKSEL: Clock Select

Bit	7	6	5	4	3	2	1	0
Name	CLKRDY	CLKDIV[2:0]				CLKSEL[2:0]		
Type	R	R/W			R/W	R/W		
Reset	0	0	0	1	0	0	1	0

SFR Page = All Pages; SFR Address = 0xA9

Bit	Name	Function
7	CLKRDY	**System Clock Divider Clock Ready Flag.** 0: The selected clock divide setting has not been applied to the system clock. 1: The selected clock divide setting has been applied to the system clock.
6:4	CLKDIV[2:0]	**System Clock Divider Bits.** Selects the clock division to be applied to the undivided system clock source. 000: System clock is divided by 1. 001: System clock is divided by 2. 010: System clock is divided by 4. 011: System clock is divided by 8. 100: System clock is divided by 16. 101: System clock is divided by 32. 110: System clock is divided by 64. 111: System clock is divided by 128.
3	Unused	Read = 0b. Must Write 0b.
2:0	CLKSEL[2:0]	**System Clock Select.** Selects the oscillator to be used as the undivided system clock source. 000: Precision Internal Oscillator. 001: External Oscillator. 010: Low Power Oscillator divided by 8. 011: SmaRTClock Oscillator. 100: Low Power Oscillator. All other values reserved.

26. LCD Segment Driver

C8051F96x devices contain an LCD segment driver and on-chip bias generation that supports static, 2-mux, 3-mux and 4-mux LCDs with 1/2 or 1/3 bias. The on-chip charge pump with programmable output voltage allows software contrast control which is independent of the supply voltage. LCD timing is derived from the SmaRTClock oscillator to allow precise control over the refresh rate.

The C8051F96x uses special function registers (SFRs) to store the enabled/disabled state of individual LCD segments. All LCD waveforms are generated on-chip based on the contents of the LCD0Dn registers An LCD blinking function is also supported. A block diagram of the LCD segment driver is shown in Figure 26.1.

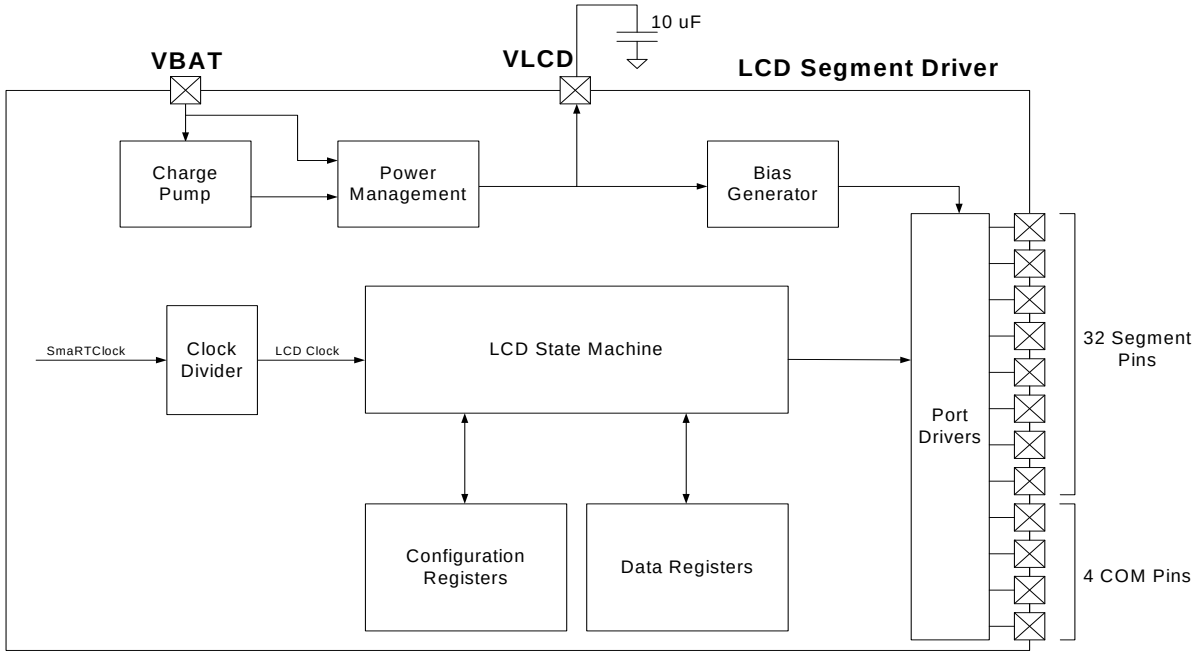

Figure 26.1. LCD Segment Driver Block Diagram

26.1. Configuring the LCD Segment Driver

The LCD segment driver supports multiple mux options: static, 2-mux, 3-mux, and 4-mux mode. It also supports 1/2 and 1/3 bias options. The desired mux mode and bias is configured through the LCD0CN register. A divide value may also be applied to the SmaRTClock output before being used as the LCD0 clock source.

The following procedure is recommended for using the LCD Segment Driver:

1. Initialize the SmaRTClock and configure the LCD clock divide settings in the LCD0CN register.
2. Determine the GPIO pins which will be used for the LCD function.
3. Configure the Port I/O pins to be used for LCD as Analog I/O.
4. Configure the LCD size, mux mode, and bias using the LCD0CN register.
5. Enable the LCD bias and clock gate by writing 0x50 to the LCD0MSCN register.
6. Configure the device into the desired Contrast Control Mode.
7. If VIO is internally or externally shorted to VBAT, disable the VLCD/VIO Supply Comparator using the

26.3.2. Contrast Control Mode 2 (Minimum Contrast Mode)

In Contrast Control Mode 2, a minimum contrast voltage is maintained, as shown in Figure 26.4. The VLCD supply is powered directly from VBAT as long as VBAT is higher than the programmable VBAT monitor threshold voltage. As soon as the VBAT supply monitor detects that VBAT has dropped below the programmed value, the charge pump will be automatically enabled in order to acheive the desired minimum contrast voltage on VLCD. Minimum Contrast Mode is selected using the following procedure:

1. Clear Bit 2 of the LCD0MSCN register to 0b (LCD0MSCN &= ~0x04)
2. Set Bit 0 of the LCD0MSCF register to 1b (LCD0MSCF |= 0x01)
3. Set Bit 3 of the LCD0PWR register to 1b (LCD0PWR |= 0x08)
4. Set Bit 7 of the LCD0VBMCN register to 1b (LCD0VBMCN |= 0x80)

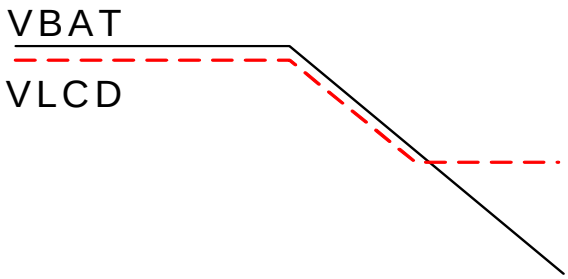

Figure 26.4. Contrast Control Mode 2

26.3.3. Contrast Control Mode 3 (Constant Contrast Mode)

In Contrast Control Mode 3, a constant contrast voltage is maintained. The VLCD supply is regulated to the programmed contrast voltage using a variable resistor between VBAT and VLCD as long as VBAT is higher than the programmable VBAT monitor threshold voltage. As soon as the VBAT supply monitor detects that VBAT has dropped below the programmed value, the charge pump will be automatically enabled in order to acheive the desired contrast voltage on VLCD. Constant Contrast Mode is selected using the following procedure:

1. Set Bit 2 of the LCD0MSCN register to 1b (LCD0MSCN |= 0x04)
2. Clear Bit 0 of the LCD0MSCF register to 0b (LCD0MSCF &= ~0x01)
3. Set Bit 3 of the LCD0PWR register to 1b (LCD0PWR |= 0x08)
4. Set Bit 7 of the LCD0VBMCN register to 1b (LCD0VBMCN |= 0x80)

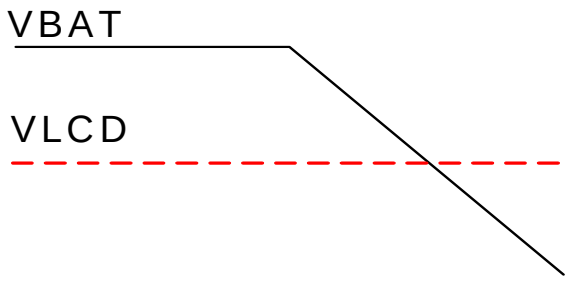

Figure 26.5. Contrast Control Mode 3

27.1.3. Interfacing Port I/O to High Voltage Logic

All Port I/O configured for digital, open-drain operation are capable of interfacing to digital logic operating at a supply voltage up to VBAT + 2.0 V. An external pull-up resistor to the higher supply voltage is typically required for most systems.

27.1.4. Increasing Port I/O Drive Strength

Port I/O output drivers support a high and low drive strength; the default is low drive strength. The drive strength of a Port I/O can be configured using the PnDRV registers. See Section “4. Electrical Characteristics” on page 56 for the difference in output drive strength between the two modes.

27.2. Assigning Port I/O Pins to Analog and Digital Functions

Port I/O pins P0.0–P2.6 can be assigned to various analog, digital, and external interrupt functions. The Port pins assigned to analog functions should be configured for analog I/O and Port pins assigned to digital or external interrupt functions should be configured for digital I/O.

27.2.1. Assigning Port I/O Pins to Analog Functions

Table 27.1 shows all available analog functions that need Port I/O assignments. **Port pins selected for these analog functions should have their digital drivers disabled (PnMDOUT.n = 0 and Port Latch = 1) and their corresponding bit in PnSKIP set to 1.** This reserves the pin for use by the analog function and does not allow it to be claimed by the Crossbar. Table 27.1 shows the potential mapping of Port I/O to each analog function.

Table 27.1. Port I/O Assignment for Analog Functions

Analog Function	Potentially Assignable Port Pins	SFR(s) used for Assignment
ADC Input	P0.0–P0.7, P1.4–P2.3	ADC0MX, PnSKIP
Comparator0 Input	P0.0–P0.7, P1.4–P2.3	CPT0MX, PnSKIP
Comparator1 Input	P0.0–P0.7, P1.4–P2.3	CPT1MX, PnSKIP
LCD Pins (LCD0)	P2.4–P6.7	PnMDIN, PnSKIP
Pulse Counter (PC0)	P1.0, P1.1	P1MDIN, PnSKIP
Voltage Reference (VREF0)	P0.0	REF0CN, PnSKIP
Analog Ground Reference (AGND)	P0.1	REF0CN, PnSKIP
Current Reference (IREF0)	P0.7	IREF0CN, PnSKIP
External Oscillator Input (XTAL1)	P0.2	OSCXCN, PnSKIP
External Oscillator Output (XTAL2)	P0.3	OSCXCN, PnSKIP
SmaRTClock Input (XTAL3)	P1.2	P1MDIN, PnSKIP
SmaRTClock Output (XTAL4)	P1.3	P1MDIN, PnSKIP

29.2. Operational Modes

UART0 provides standard asynchronous, full duplex communication. The UART mode (8-bit or 9-bit) is selected by the S0MODE bit (SCON0.7). Typical UART connection options are shown below.

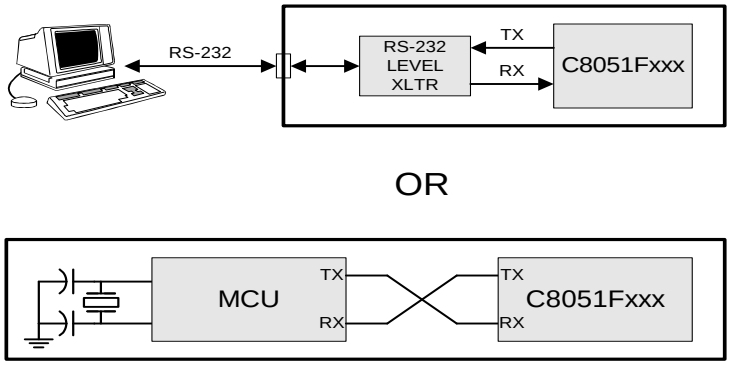

Figure 29.3. UART Interconnect Diagram

29.2.1. 8-Bit UART

8-Bit UART mode uses a total of 10 bits per data byte: one start bit, eight data bits (LSB first), and one stop bit. Data are transmitted LSB first from the TX0 pin and received at the RX0 pin. On receive, the eight data bits are stored in SBUF0 and the stop bit goes into RB80 (SCON0.2).

Data transmission begins when software writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to logic 1. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: RI0 must be logic 0, and if MCE0 is logic 1, the stop bit must be logic 1. In the event of a receive data overrun, the first received 8 bits are latched into the SBUF0 receive register and the following overrun data bits are lost.

If these conditions are met, the eight bits of data is stored in SBUF0, the stop bit is stored in RB80 and the RI0 flag is set. If these conditions are not met, SBUF0 and RB80 will not be loaded and the RI0 flag will not be set. An interrupt will occur if enabled when either TI0 or RI0 is set.

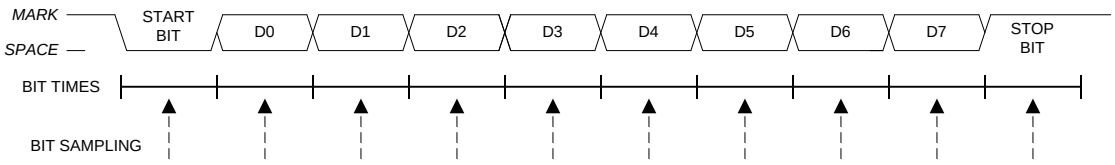

Figure 29.4. 8-Bit UART Timing Diagram

29.2.2. 9-Bit UART

9-bit UART mode uses a total of eleven bits per data byte: a start bit, 8 data bits (LSB first), a programmable ninth data bit, and a stop bit. The state of the ninth transmit data bit is determined by the value in TB80 (SCON0.3), which is assigned by user software. It can be assigned the value of the parity flag (bit P in register PSW) for error detection, or used in multiprocessor communications. On receive, the ninth data bit goes into RB80 (SCON0.2) and the stop bit is ignored.

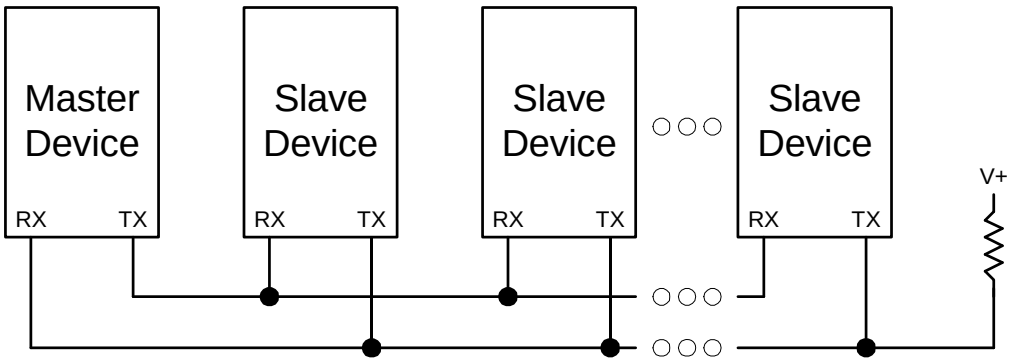

Figure 29.6. UART Multi-Processor Mode Interconnect Diagram

Table 29.1. Timer Settings for Standard Baud Rates Using The Internal 24.5 MHz Oscillator

	Frequency: 24.5 MHz						
	Target Baud Rate (bps)	Baud Rate % Error	Oscillator Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select)[1]	T1M[1]	Timer 1 Reload Value (hex)
SYSCLK from Internal Osc.	230400	–0.32%	106	SYSCLK	XX[2]	1	0xCB
	115200	–0.32%	212	SYSCLK	XX	1	0x96
	57600	0.15%	426	SYSCLK	XX	1	0x2B
	28800	–0.32%	848	SYSCLK/4	01	0	0x96
	14400	0.15%	1704	SYSCLK/12	00	0	0xB9
	9600	–0.32%	2544	SYSCLK/12	00	0	0x96
	2400	–0.32%	10176	SYSCLK/48	10	0	0x96
	1200	0.15%	20448	SYSCLK/48	10	0	0x2B

Notes:
1. SCA1–SCA0 and T1M bit definitions can be found in Section 32.1.
2. X = Don't care.

Table 29.2. Timer Settings for Standard Baud Rates Using an External 22.1184 MHz Oscillator

	Frequency: 22.1184 MHz						
	Target Baud Rate (bps)	Baud Rate % Error	Oscillator Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select)[1]	T1M[1]	Timer 1 Reload Value (hex)
SYSCLK from External Osc.	230400	0.00%	96	SYSCLK	XX[2]	1	0xD0
	115200	0.00%	192	SYSCLK	XX	1	0xA0
	57600	0.00%	384	SYSCLK	XX	1	0x40
	28800	0.00%	768	SYSCLK / 12	00	0	0xE0
	14400	0.00%	1536	SYSCLK / 12	00	0	0xC0
	9600	0.00%	2304	SYSCLK / 12	00	0	0xA0
	2400	0.00%	9216	SYSCLK / 48	10	0	0xA0
	1200	0.00%	18432	SYSCLK / 48	10	0	0x40

Table 33.2. PCA0CPM and PCA0PWM Bit Settings for PCA Capture/Compare Modules

Operational Mode	PCA0CPMn								PCA0PWM				
Software Timer	X	C	0	0	1	0	0	A	0	X	B	XXX	XX
High Speed Output	X	C	0	0	1	1	0	A	0	X	B	XXX	XX
Frequency Output	X	C	0	0	0	1	1	A	0	X	B	XXX	XX
8-Bit Pulse Width Modulator (Note 7)	0	C	0	0	E	0	1	A	0	X	B	XXX	00
9-Bit Pulse Width Modulator (Note 7)	0	C	0	0	E	0	1	A	D	X	B	XXX	01
10-Bit Pulse Width Modulator (Note 7)	0	C	0	0	E	0	1	A	D	X	B	XXX	10
11-Bit Pulse Width Modulator (Note 7)	0	C	0	0	E	0	1	A	D	X	B	XXX	11
16-Bit Pulse Width Modulator	1	C	0	0	E	0	1	A	0	X	B	XXX	XX

Notes:
1. X = Don't Care (no functional difference for individual module if 1 or 0).
2. A = Enable interrupts for this module (PCA interrupt triggered on CCFn set to 1).
3. B = Enable 8th, 9th, 10th or 11th bit overflow interrupt (Depends on setting of CLSEL[1:0]).
4. C = When set to 0, the digital comparator is off. For high speed and frequency output modes, the associated pin will not toggle. In any of the PWM modes, this generates a 0% duty cycle (output = 0).
5. D = Selects whether the Capture/Compare register (0) or the Auto-Reload register (1) for the associated channel is accessed via addresses PCA0CPHn and PCA0CPLn.
6. E = When set, a match event will cause the CCFn flag for the associated channel to be set.
7. All modules set to 8, 9, 10 or 11-bit PWM mode use the same cycle length setting.

33.3.1. Edge-triggered Capture Mode

In this mode, a valid transition on the CEXn pin causes the PCA to capture the value of the PCA counter/timer and load it into the corresponding module's 16-bit capture/compare register (PCA0CPLn and PCA0CPHn). The CAPPn and CAPNn bits in the PCA0CPMn register are used to select the type of transition that triggers the capture: low-to-high transition (positive edge), high-to-low transition (negative edge), or either transition (positive or negative edge). When a capture occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1. An interrupt request is generated if the CCFn interrupt for that module is enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. If both CAPPn and CAPNn bits are set to logic 1, then the state of the Port pin associated with CEXn can be read directly to determine whether a rising-edge or falling-edge caused the capture.

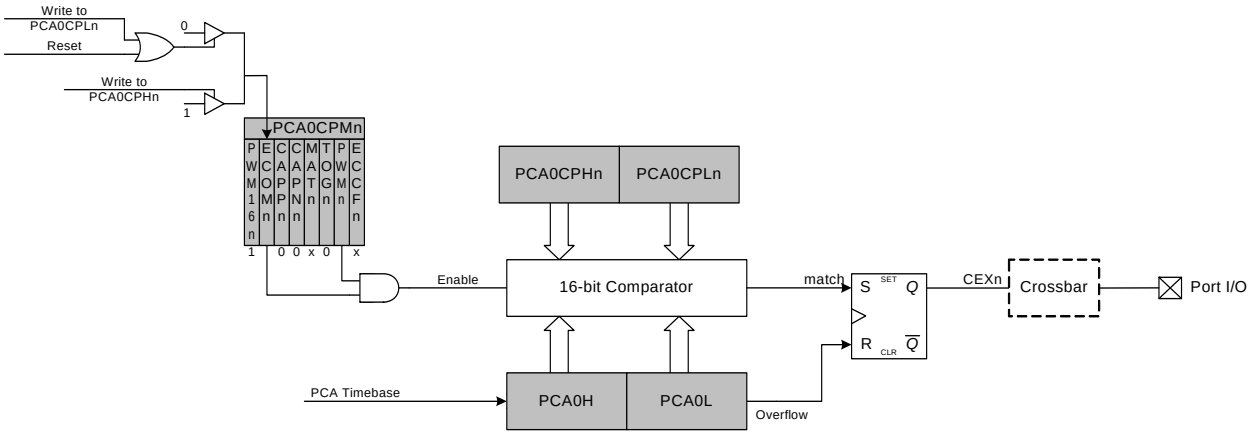

Figure 33.10. PCA 16-Bit PWM Mode

33.4. Watchdog Timer Mode

A programmable watchdog timer (WDT) function is available through the PCA Module 5. The WDT is used to generate a reset if the time between writes to the WDT update register (PCA0CPH2) exceed a specified limit. The WDT can be configured and enabled/disabled as needed by software.

With the WDTE bit set in the PCA0MD register, Module 5 operates as a watchdog timer (WDT). The Module 5 high byte is compared to the PCA counter high byte; the Module 5 low byte holds the offset to be used when WDT updates are performed. **The Watchdog Timer is enabled on reset. Writes to some PCA registers are restricted while the Watchdog Timer is enabled.** The WDT will generate a reset shortly after code begins execution. To avoid this reset, the WDT should be explicitly disabled (and optionally re-configured and re-enabled if it is used in the system).

33.4.1. Watchdog Timer Operation

While the WDT is enabled:

- PCA counter is forced on.
- Writes to PCA0L and PCA0H are not allowed.
- PCA clock source bits (CPS2–CPS0) are frozen.
- PCA Idle control bit (CIDL) is frozen.
- Module 5 is forced into software timer mode.
- Writes to the Module 5 mode register (PCA0CPM5) are disabled.

While the WDT is enabled, writes to the CR bit will not change the PCA counter state; the counter will run until the WDT is disabled. The PCA counter run control bit (CR) will read zero if the WDT is enabled but user software has not enabled the PCA counter. If a match occurs between PCA0CPH5 and PCA0H while the WDT is enabled, a reset will be generated. To prevent a WDT reset, the WDT may be updated with a write of any value to PCA0CPH5. Upon a PCA0CPH5 write, PCA0H plus the offset held in PCA0CPL5 is loaded into PCA0CPH5. (See Figure 33.11.)